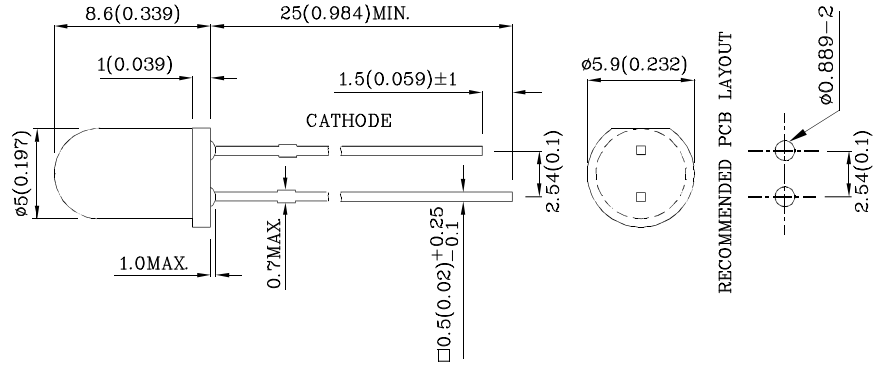


Features

- 5mm package with built-in blinking IC
- Blinking frequency: 3.0Hz to 1.5Hz
- Operation voltage: 3.5V to 14V
- RoHS compliant.



Package Schematics



Notes:

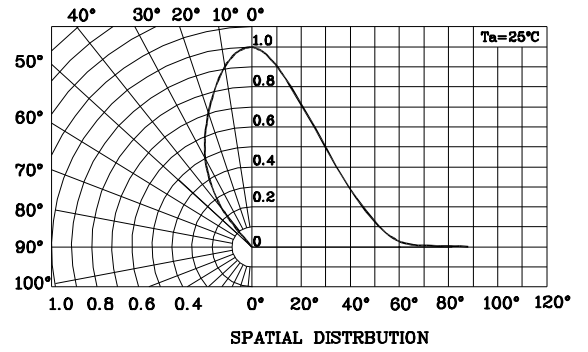
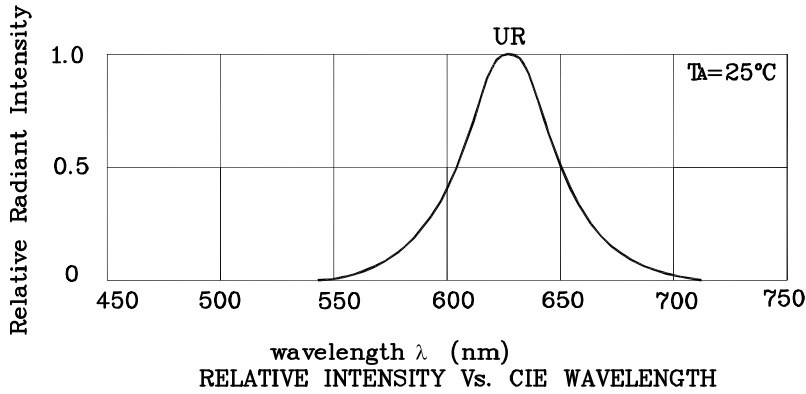
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

| Absolute Maximum Ratings ($T_A=25^\circ\text{C}$) | | UR (GaAsP/GaP) | Unit |
|--|---------------------|-------------------|------|
| Reverse Voltage | V_R | 0.5 | V |
| Forward Voltage | V_F | 14 | V |
| Power Dissipation | P_D | 310 | mW |
| Operating Temperature | T_A | -40 ~ +70 | °C |
| Storage Temperature | T_{stg} | -40 ~ +85 | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3 Seconds | | |
| Lead Solder Temperature [5mm Below Package Base] | 260°C For 5 Seconds | | |

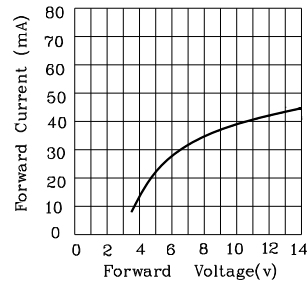
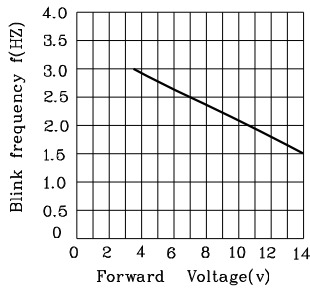
| Operating Characteristics ($T_A=25^\circ\text{C}$) | | UR (GaAsP/GaP) | Unit |
|--|-----------------|-------------------|------|
| Forward Current (Min.) ($V_F=3.5\text{V}$) | I_F | 8 | mA |
| Forward Current (Typ.) ($V_F=5\text{V}$) | I_F | 22 | mA |
| Supply Current (Typ.) ($V_F=3.5\text{V}$) | I_{SON} | 8 | mA |
| Supply Current (Typ.) ($V_F=14\text{V}$) | I_{SON} | 44 | mA |
| Blink Frequency (Min.~Max.) ($V_F=3.5\text{V}\sim 14\text{V}$) | f | 1.5~3 | Hz |
| Wavelength of Peak Emission CIE127-2007* (Typ.) | λ_P | 627* | nm |
| Wavelength of Dominant Emission CIE127-2007* (Typ.) | λ_D | 617* | nm |
| Spectral Line Full Width At Half- Maximum (Typ.) | $\Delta\lambda$ | 45 | nm |

| Part Number | Emitting Color | Emitting Material | Lens-color | Luminous Intensity CIE127-2007* ($V_F=9\text{V}$) mcd | | Wavelength CIE127-2007* nm λ_P | Viewing Angle 2 θ 1/2 |
|-------------|----------------|-------------------|--------------|--|-----------|---|---------------------------------|
| | | | | min. | typ. | | |
| XBUR53D | Red | GaAsP/GaP | Red Diffused | 18 12* | 39 24* | 627* | 60° |

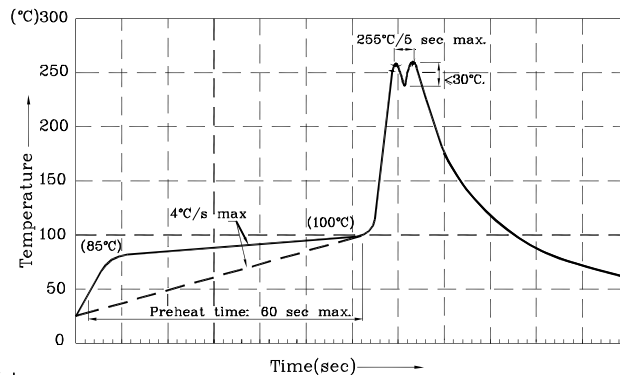
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ UR



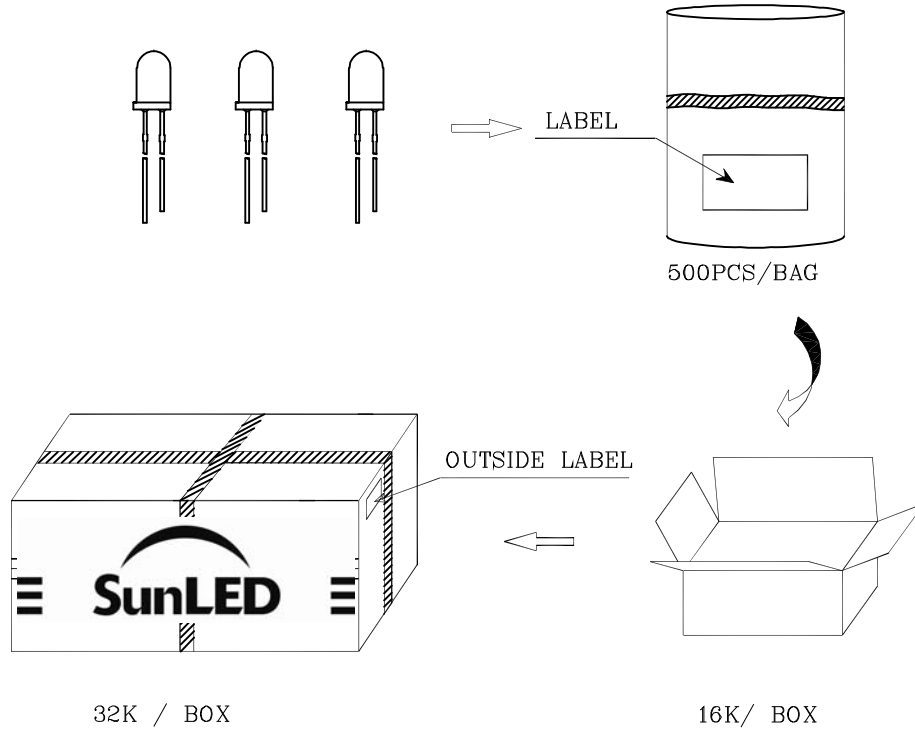
Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)





Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

PACKING & LABEL SPECIFICATIONS



| | | |
|--|--|-------------------------------------|
|  | | Q.C. Q C XX XX XXXX PASSED |
| P/NO : XBxx53x | | |
| QTY : 500 pcs | | CODE: XXX |
| S/N : XX | | |
| LOT NO: | | |
|  XXXXXXXXXXXXXXXXXXXXXXXX | | |
| RoHS Compliant | | |

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1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>